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Filed

09/728,038

Dec, 1, 2000

Request for access
2/4/04
JMC

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United States Patent Application Publication No. 2002/106651/6, page, line

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US 20020068516A1

(19) **United States**(12) **Patent Application Publication** (10) **Pub. No.: US 2002/0068516 A1**

Chen et al.

(43) **Pub. Date:****Jun. 6, 2002**(54) **APPARATUS AND METHOD FOR
CONTROLLED DELIVERY OF SLURRY TO
A REGION OF A POLISHING DEVICE****Publication Classification**

(51) **Int. Cl.⁷** B24B 5/00; B24B 29/00;
B24D 11/00
(52) **U.S. Cl.** 451/285; 451/287; 451/527;
451/539

(75) **Inventors:** Hung Chen, San Jose, CA (US);
Sidney P. Huey, Milpitas, CA (US)

Correspondence Address:
Patent Counsel
Applied Materials, Inc.
P.O. Box 450-A
Santa Clara, CA 95052 (US)

(57) **ABSTRACT**

A polishing pad and/or platen for use in a chemical mechanical polishing system is provided. The polishing pad and/or platen have slurry distribution/retaining grooves formed on a surface thereof. In one embodiment, the grooves are formed on the upper polishing surface of a pad for use in a rotary or linear polishing system. In another embodiment, an upper mounting surface of a platen is patterned with grooves. The grooves are adapted to direct the flow of slurry inwardly from a perimeter portion of the pad/platen. In operation, the grooves provide uniform distribution of slurry to areas on a polishing pad/platen.

(73) **Assignee:** Applied Materials, Inc(21) **Appl. No.:** 09/728,038(22) **Filed:** Dec. 1, 2000**Related U.S. Application Data**(63) **Non-provisional of provisional application No.**
60/170,596, filed on Dec. 13, 1999.